Notes
1. Assume no forced air flow.
2. D1, D2 and D4 need heat sinks.
3. Assign large copper area to R6 to dissipate heat.
4. Loop may need a tweak once component selection is confirmed.

*All components highlighted by dark yellow boxes are not part of original PCB design and layout! These need to be implemented into the PCB layout for proper operation!

**Original PCB design has 50ohm resistors for R1 and R2, but two 100ohm resistors in parallel for each of R1 and R2 is recommended for better heat dissipation

***Use only one, either L1 or L2. Both were placed here in order to make available both SMT and Through Hole mounting areas on the PCB

Dr. Dongbing Zhang

Public Release

Designed for:

PMP7806 Bench R1_refined.SchDoc

Variant name not interpreted

Project Title:

BODE+

File:

Assembly Variant:

Not in version control

Drawn By:

Dongbing Zhang

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